PCN Number:	20191017000.2		PCN Date:	Oct 28, 2019
Title:	Qualification of SCT as an additional Test Site for select devices			
Customer Contact:	PCN Manager	Dept:	Quality Services	
Proposed 1st Ship Date:	Apr 28, 2020			

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of SCT as additional Test Site for select devices listed in the "Product Affected" Section.

	Current	Proposed
Test Site	DFAB	SCT

Reason for Change:

Continuity of supply by adding additional test capacity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

None

Product Affected:

S0907058A3PFPR	TPIC7218QPFPRQ1

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com